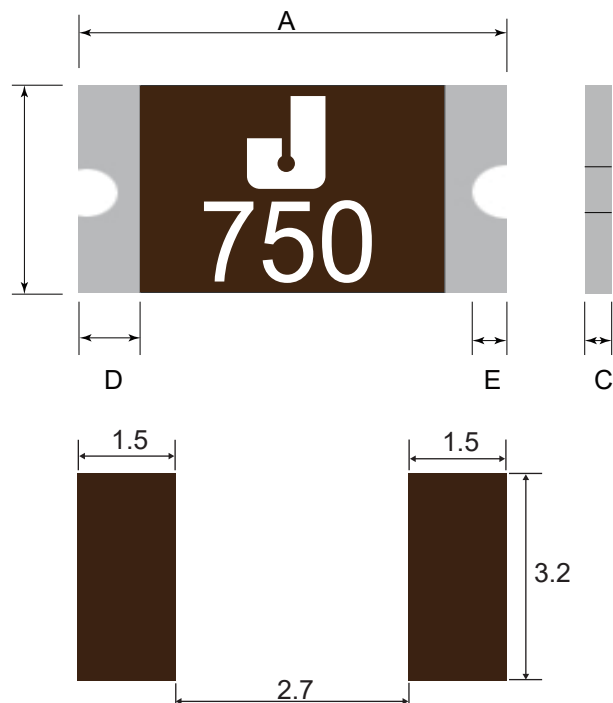


Specification Sheet



Terminal Pad Solderability

Meets EIA Specification RS186-9E
And ANSI/J-STD-002 Category 3.

Terminal Pad Materials

Tin-Plated Nickel-Copper
Solder Material: Matte Tin (Sn)
Lead-Free, RoHS Compliant

Marking

Part Identification
ASMD1812SL750-16V = J750

Recommended Pad layout(mm)

Physical Dimensions(mm.)

Model	A		B		C		D		E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.
ASMD1812SL750-16V	4.37	4.73	3.07	3.41	0.60	1.20	0.30	1.20	0.20

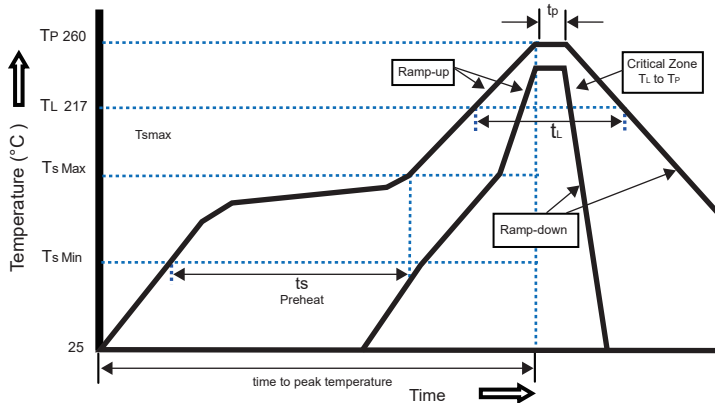
Electrical Characteristics

Model	I _{hold} @25°C (A)	I _{hold} @70°C (A)	V _{max} (V)	I _{max} (A)	P _d Typ. (W)	Thermal Cut Off (°C)		Resistance	
						5A		R _{i min} (Ω)	R _{1max} (Ω)
						Min.	Max.		
ASMD1812SL750-16V	7.50	5.00	16.0	15.0	1.5	70	100	0.0005	0.006

Thermal Derating Chart

Model	Maximum ambient operating temperature (T _{mao}) vs. hold current (I _{hold})				
	- 20°C	0°C	25°C	70°C	85°C
ASMD1812SL750-16V	9.50	8.35	7.50	5.00	3.90

Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate(Ts _{Max} to Tp)	3°C/s Max.
-Temperature Min(Ts _{Min})	150°C
Preheat -Temperature Max(Ts _{Max})	200°C
-Time(ts _{Min} to ts _{Max})	60~180 s
Time maintained -Temperature(TL)	217°C
above: -Time(tL)	60~150 s
Peak/Classification Temperature(Tp)	260 ^{+0/-5} °C
Time within 5°C of actual peak temperature(tp)	20~40 s
Ramp down rate	6°C/s Max.
Time 25°C to peak temperature	8 min. Max.

- ◆ All temperature refer to topside of the package, measured on the package body surface
- ◆ If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements
- ◆ Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead
- ◆ Recommended maximum paste thickness is 0.25mm (0.010inch)
- ◆ Devices can be cleaned using standard industry methods and solvents

Packaging Quantity

Model	Quantity
ASMD1812SL750-16V	1,500 pcs/reel